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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:

Bharat Shivkumar et al.

Date: June 16, 2005

Serial No.: 09/812,027

Group Art Unit: 2813

Filed: March 19, 2001

Examiner: James Mitchell

Notice of Allowance Dated: May 27, 2005

Confirmation No. 4072

For SEMICONDUCTOR MULTICHIP MODULE PACKAGE WITH IMPROVED  
THERMAL PERFORMANCE; REDUCED SIZE AND IMPROVED MOISTURE  
RESISTANCE

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450  
Attention: Official Draftsperson

SUBMISSION OF FORMAL DRAWINGS

Sir:

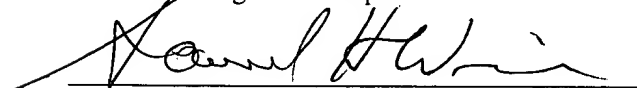
Enclosed herewith please find FOUR (4) sheets of replacement drawings containing  
Figures 1-4 for the above-identified application.

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Respectfully submitted,

Samuel H. Weiner


Name of applicant, assignee or  
Registered Representative

  
Signature

June 16, 2005

Date of Signature

SHW:fs  
Enclosure

  
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